

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.48657	100.0	5.2
<b>Subtotal</b>				<b>0.48657</b>	<b>100</b>	<b>5.2</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03752	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01126	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03752	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.43538	99.77	400.0777
<b>Subtotal</b>				<b>37.52168</b>	<b>100</b>	<b>401</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.84304	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.923	10.0	63.3
	Filler	Silica fused	60676-86-0	50.34549	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11846	0.2	1.266
<b>Subtotal</b>				<b>59.22999</b>	<b>100</b>	<b>633</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.33926	100.0	25
<b>Subtotal</b>				<b>2.33926</b>	<b>100</b>	<b>25</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.03572	100.0	0.3817
	Pure metal	Aluminium (Al)	7429-90-5	0.09673	100.0	1.03378
<b>Subtotal</b>				<b>0.13245</b>	<b>200</b>	<b>1.41548</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.0058	2.0	0.062
	Lead alloy	Silver (Ag)	7440-22-4	0.00725	2.5	0.0775
	Lead alloy	Lead (Pb)	7439-92-1	0.27701	95.5	2.9605
<b>Subtotal</b>				<b>0.29006</b>	<b>100</b>	<b>3.1</b>
<b>Total</b>				<b>100.00001</b>	<b>100</b>	<b>1068.71548</b>

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